

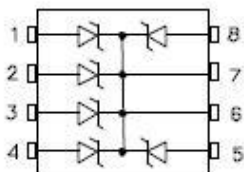
SMDA03C-5 THRU SMDA24C-5 TVS ARRAY SERIES



Description

The SMDAXXC-5 series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect combinations of five bidirectional lines.

Schematic & Pin Configuration



Features

- Protects 3.3, 5, 12, 15, 24 V Components
- Bidirectional
- Provides Electrically Isolated Protection
- 300 W @ 8/20 us
- Protects 5 Lines
- SO-8 Packaging
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Mechanical Characteristics

- SO-8 Surface Mount Package
- Approximate Weight: 0.1 grams
- PIN #1 Indicator: DOT on top of package
- Packaging: Tubes or Tape & Reel per EIA Standard 481

Application

- RS-232 & RS-422 data lines
- Microprocessor Based Equipment
- Notebooks, Desktops, 7Services
- LAN/WAN Equipment
- Serial and Parallel Port
- Peripherals

Absolute Maximum Ratings:

Parameter	Symbol	Value	Units
Peak Pulse Power, 8/20 μ s Wave shape	P	300	W
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{stg}	-55 to +150	°C
Lead Soldering Temperature	T _L	260 (10 Sec.)	°C

Electrical Characteristics@25°C

Part Number	Stand-off Voltage V_{wm} (V) Max	Breakdown Voltage V_{BR} @1mA (V) Min	Clamping Voltage V_c @ 1 A (V) Max	Leakage Current I_R @ V_{wm} (uA) Max	Capacitance (f = 1MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} a(V_{BR}) mv/°C Max
SMDA03C-5	3.3	4	7	200	300	-5
SMDA05C-5	5.0	6	9.8	40	200	3
SMDA12C-5	12.0	13.3	19	1	75	10
SMDA15C-5	15.0	16.7	24	1	50	13
SMDA24C-5	24.0	26.7	43	1	35	30

Ratings and Characteristics Curves

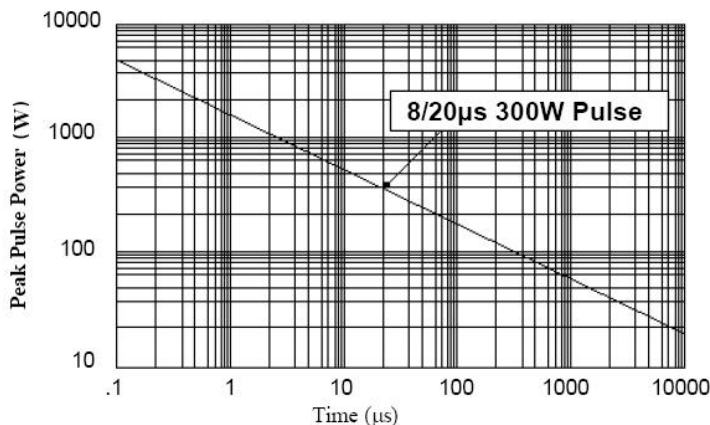


Figure 1. Peak Pulse Power Vs Pulse Time (µs)

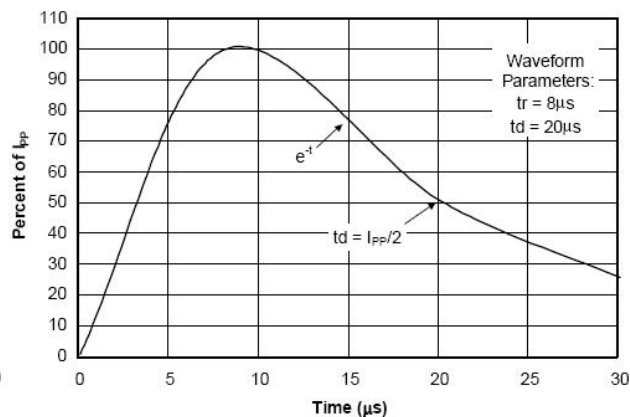


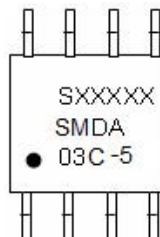
Figure 2. Pulse Wave Form

Ordering Information

Device	Package	Shipping
SMDA03C-5 THRU SMDA24C-5	SO-8 (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

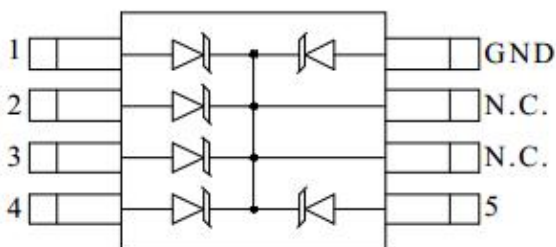


Where XXXXX is YYWWL

SMDA03C-5 = Part Number
S = S
YY = Year
WW = Week
L = Lot Number

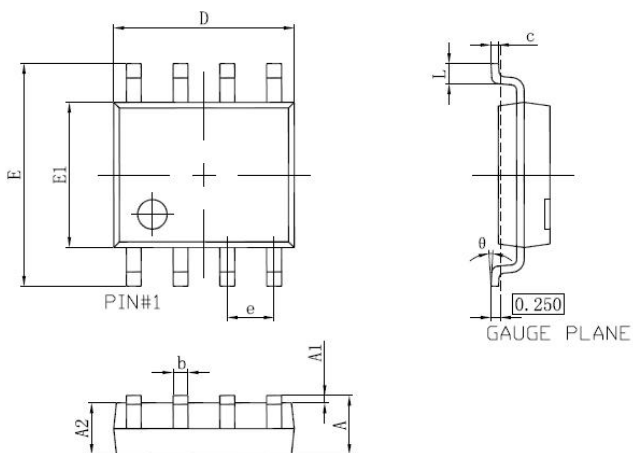
Cautions: Molding resin
Epoxy resin UL:94V-0

Circuit Diagram



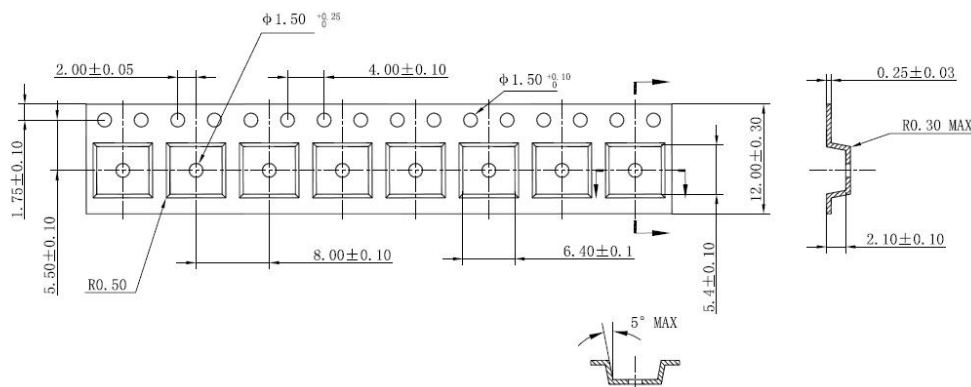
Note: Pins 1, 2, 3, 4, and 5 are connected to the lines that are to be protected. Pin 8 is connected to ground. The ground connections should be made directly to the ground plane for best results. The path length is kept as possible to reduce the effects of parasitic inductance in the board traces. Pins 6 and 7 are not connected.

Mechanical Dimensions SO-8



SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
θ	0°	8°	0°	8°

Carrier Tape Specification SO-8



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